Ratiometric configuration of 2 x (2-wire or 4-wire) RTDs

Insert R17 and R19 for 2-wire PT
Insert R18 and R20 for 2-wire PT

External Access

UART with VCC and GND

LDO: 2.5V or 2.8V version

ASD1x2C_Rev.png, Page 1 of 5

LaunchPad/BoosterPack Connectors

Default is UART (ASD1x2C_Rev) w/o 10 kΩ R21/22
Place R21/22 if I2C (ASD1x2C_Rev)

TE Connectivity Terminal blocks used

R13: High Precision Reference Resistor: 0.1%, 25ppm/C

SensRTD1_N
SensRTD2_N

VIN
VCC
External access

Engineer:
File:
Designed for:
Contact:

Related Information:

Modify your design to meet your own needs. Texas Instruments and/or its licensors do not warrant that the design will meet the specifications in this data sheet or that the design will meet the specifications in your application. Texas Instruments and/or its licensors do not warrant that the design is production worthy. You should completely test and verify your design implementation to confirm the system functionality for your application.

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Note: All information provided is subject to change without notice.

To obtain the latest information, go to the Texas Instruments website.
Heat Meter dual 2-/4-wire RTD measurement

**Project Title:**

**Designed for:** Public Release

**Assembly Variant:** 001

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**Variant/Label Table**

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>4-wire PT500</td>
</tr>
<tr>
<td>002</td>
<td>2-wire PT500</td>
</tr>
</tbody>
</table>

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**Assembly Notes:**

- **ZZ1:** This Assembly Note is for PCB labels only.
- **ZZ2:** These assemblies are ESD sensitive, ESD precautions shall be observed.
- **ZZ3:** These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- **ZZ4:** These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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**You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.**

**Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).**

**Update the Label Text in the Label Table as needed for each Assembly Variant.**

**You should delete this note too.**
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